



Case No.: AMKOR-017A
Patent Appln.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jong Sik Paek

Serial No.: 10/043,946

Filed: 01/11/2002

For: SEMICONDUCTOR PACKAGE
WITH STACKED DIES

Group No.: 2812

Examiner: Simkovic, Viktor

AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the Restriction Requirement mailed July 17, 2002, in relation to the above-identified patent application, please amend the application as follows:

In the Claims:

Please cancel Claims 12-18.

Please add the following new claims into prosecution:

sub 67
a

19. (New) A semiconductor package comprising:

a plurality of leads;

a first semiconductor die including a plurality of bond pads disposed thereon, the